

S/N 09/965,555PATENTIN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Michele J. Berry

Examiner: Luan Thai

Serial No.: 09/965,555

Group Art Unit: 2827

Filed: September 27, 2001

Docket: 884,548US1

Title: ENCAPSULATION OF PIN SOLDER FOR MAINTAINING ACCURACY IN
PIN POSITION

Assignee: Intel Corporation

Customer No: 21186

INFORMATION DISCLOSURE STATEMENT**FAX RECEIVED**Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

SEP 09 2005

OFFICE OF PETITIONS

In compliance with the duty imposed by 37 C.F.R. § 1.56, and in accordance with 37 C.F.R. §§ 1.97 *et. seq.*, the enclosed materials are brought to the attention of the Examiner for consideration in connection with the above-identified patent application. Applicant respectfully requests that this Information Disclosure Statement be entered and the documents listed on the attached Form 1449 be considered by the Examiner and made of record. Pursuant to the provisions of MPEP 609, Applicant requests that a copy of the 1449 form, initialed as being considered by the Examiner, be returned to the Applicant with the next official communication.

One of the listed documents (U.S. 6,209,196) was discovered as a result of the Written Opinion issued in Applicants' corresponding foreign patent application (PCT/US02/30625). This Written Opinion is also cited on the attached PTO 1449 Form and a copy is enclosed.

Pursuant to 37 C.F.R. §1.97(b), it is believed that no fee or statement is required with the Information Disclosure Statement.

Best Available Copy

INFORMATION DISCLOSURE STATEMENT

Serial No :09/965555

Filing Date: September 27, 2001

Title: ENCAPSULATION OF PIN SOLDER FOR MAINTAINING ACCURACY IN PIN POSITION

Assignee: Intel Corporation

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Dkt: 884.548US1 (INTEL)

The Examiner is invited to contact the Applicant's Representative at the below-listed telephone number if there are any questions regarding this communication.

Pursuant to 37 C.F.R. 1.98(a)(2), Applicant believes that copies of cited U.S. Patents and Published Applications are no longer required to be provided to the Office. Notification of this change was provided in the United States Patent and Trademark Office OG Notices dated October 12, 2004. Thus, Applicant has not included copies of any US Patents or Published Applications cited with this submission. Should the Office require copies to be provided, Applicant respectfully requests that notice of such requirement be directed to Applicant's below-signed representative. Applicant acknowledges the requirement to submit copies of foreign patent documents and non-patent literature in accordance with 37 C.F.R. 1.98(a)(2).

Respectfully submitted,

MICHELE J. BERRY

By his Representatives,

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.
Attorneys for Intel Corporation
P.O. Box 2938
Minneapolis, MN 55402
(612) 373-6973

Date 9 September 2005

By

Robert E. Mates
Reg. No. 35,271

I hereby certify that this paper is being transmitted by facsimile to the U.S. Patent and Trademark Office on the date shown below.

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Substitute for form 1449A/PTO INFORMATION DISCLOSURE STATEMENT BY APPLICANT (Use as many sheets as necessary)	Complete if Known	
	Application Number	09/965,555
	Filing Date	September 27, 2001
	First Named Inventor	Berry, Michele
	Group Art Unit	2827
	Examiner Name	Thai, Luan
Sheet 1 of 1	Attorney Docket No: 884.548US1	

US PATENT DOCUMENTS				
Examiner Initial *	USP Document Number	Publication Date	Name of Patentee or Applicant of cited Document	Filing Date if Appropriate
	US-5,759,730	06/02/1998	Hermansen, R. D., et al.	07/21/1997
	US-6,209,196	04/03/2001	Ozono, , et al.	01/21/1999

OTHER DOCUMENTS -- NON PATENT LITERATURE DOCUMENTS			
Examiner Initials*	Cite No *	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T*
		Written Opinion for PCT/US02/30625	

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OFFICE OF PETITIONS

EXAMINER

DATE CONSIDERED

Substitute Disclosure Statement Form (PTO-1449)

* EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 600. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant. Applicant's unique citation designation number (optional) Applicant is to place a check mark here if English language Translation is attached

PATENT COOPERATION TREATY

From the
INTERNATIONAL PRELIMINARY EXAMINING AUTHORITY

To:
CHARLES E. STEFFEY
SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P. A.
P. O. BOX 2938
MINNEAPOLIS, MN 55402

PCT

WRITTEN OPINION

(PCT Rule 66)

Applicant's or agent's file reference		Date of Mailing (day/month/year)
884,548W01		REPLY DUE within 2 months/days from the above date of mailing
International application No.	International filing date (day/month/year)	Priority date (day/month/year)
PCT/US02/30625	26 September 2002 (26.09.2002)	27 September 2001 (27.09.2001)
International Patent Classification (IPC) or both national classification and IPC		
IPC(7): H01L 21/44; H01L 23/48, 23/48, 23/52 and US Cl.: 438/61; 3; 257/697, 779, etc. 1		
Applicant		
INTEL CORPORATION		

- This written opinion is the first (first, etc.) drawn by this International Preliminary Examining Authority.
- This opinion contains indications relating to the following items:
 - ☒ Basis of the opinion
 - ☐ Priority
 - ☐ Non-establishment of opinion with regard to novelty, inventive step and industrial applicability
 - ☐ Lack of unity of invention
 - ☒ Reasoned statement under Rule 66.2 (a)(ii) with regard to novelty, inventive step or industrial applicability, citations and explanations supporting such statement
 - ☐ Certain documents cited
 - ☐ Certain defects in the international application
 - ☐ Certain observations on the international application
- The applicant is hereby invited to reply to this opinion.

When? See the time limit indicated above. ~~The applicant may, before the expiration of that time limit, request this Authority to grant an extension. See rule 66.2(d).~~

How? By submitting a written reply, accompanied, where appropriate, by amendments, according to Rule 66.3. For the form and the language of the amendments, see Rules 66.8 and 66.9.

Also For an additional opportunity to submit amendments, see Rule 66.4.
For the examiner's obligation to consider amendments and/or arguments, see Rule 66.4 bis.
For an informal communication with the examiner, see Rule 66.6

If no reply is filed, the international preliminary examination report will be established on the basis of this opinion.
- The final date by which the international preliminary examination report must be established according to Rule 69.2 is: 27 January 2004 (27.01.2004).

Name and mailing address of the IPEA/US Mail Stop PCT, Attn: IPEA/US Commissioner for Patents P.O. Box 1450 Alexandria, Virginia 22313-1450 Facsimile No. (703) 305-3230	Authorized officer <i>James R. Matthews</i> William B. Baumeister Telephone No. (571) 272-1650
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Form PCT/IPEA/408 (cover sheet)(July 1998)

P408

JUL 11 2005

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PATENT COOPERATION TREATY

From the
INTERNATIONAL PRELIMINARY EXAMINING AUTHORITY

To:
CHARLES E. STEFFBY
SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P. A.
P. O. BOX 2938
MINNEAPOLIS, MN 55402

PCT

WRITTEN OPINION

(PCT Rule 66)

Applicant's or agent's file reference		Date of Mailing (day/month/year)
884 548W01		08 JUL 2003
International application No.	International filing date (day/month/year)	Priority date (day/month/year)
PCT/US02/30625	26 September 2002 (26.09.2002)	27 September 2001 (27.09.2001)
International Patent Classification (IPC) or both national classification and IPC		
IPC(7): H01L 21/44; H01L 23/48, 23/48, 23/52 and US CL: 438/612, 613; 257/697, 779, 780		
Applicant		
INTEL CORPORATION		

1. This written opinion is the first (first, etc.) drawn by this International Preliminary Examining Authority.
2. This opinion contains indications relating to the following items:
 - I ☒ Basis of the opinion
 - II ☐ Priority
 - III ☐ Non-establishment of opinion with regard to novelty, inventive step and industrial applicability
 - IV ☐ Lack of unity of invention
 - V ☒ Reasoned statement under Rule 66.2 (a)(ii) with regard to novelty, inventive step or industrial applicability, citations and explanations supporting such statement
 - VI ☐ Certain documents cited
 - VII ☐ Certain defects in the international application
 - VIII ☐ Certain observations on the international application
3. The applicant is hereby invited to reply to this opinion.

When? See the time limit indicated above. ~~The applicant may, before the expiration of that time limit, request this Authority to grant an extension. See rule 66.2(d).~~

How? By submitting a written reply, accompanied, where appropriate, by amendments, according to Rule 66.3. For the form and the language of the amendments, see Rules 66.8 and 66.9.

Also For an additional opportunity to submit amendments, see Rule 66.4.
For the examiner's obligation to consider amendments and/or arguments, see Rule 66.4 bis.
For an informal communication with the examiner, see Rule 66.6

If no reply is filed, the international preliminary examination report will be established on the basis of this opinion.
4. The final date by which the international preliminary examination report must be established according to Rule 69.2 is: 27 January 2004 (27.01.2004)

Name and mailing address of the IPEA/US Mail Stop PCT, Attn: IPEA/US Commissioner for Patents P.O. Box 1450 Alexandria, Virginia 22313-1450 Facsimile No. (703) 305-3230	Authorized officer <i>James R. Matthews</i> William B. Baumister Telephone No. (571) 272-1650
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Form PCT/IPEA/408 (cover sheet) (July 1998)

WRITTEN OPINION

International application No.

PCT/US02/30625

I. Basis of the opinion

1. With regard to the elements of the international application:*

- ☒ the international application as originally filed
- ☒ the description:
pages 1-5 _____, as originally filed
pages NONE _____, filed with the demand
pages NONE _____, filed with the letter of _____
- ☒ the claims:
pages 6-8 _____, as originally filed
pages NONE _____, as amended (together with any statement) under Article 19
pages NONE _____, filed with the demand
pages NONE _____, filed with the letter of _____
- ☒ the drawings:
pages 1-5 _____, as originally filed
pages NONE _____, filed with the demand
pages NONE _____, filed with the letter of _____
- ☐ the sequence listing part of the description:
pages NONE _____, as originally filed
pages NONE _____, filed with the demand
pages NONE _____, filed with the letter of _____

2. With regard to the language, all the elements marked above were available or furnished to this Authority in the language in which the international application was filed, unless otherwise indicated under this item.

These elements were available or furnished to this Authority in the following language _____ which is:

- ☐ the language of a translation furnished for the purposes of international search (under Rule 23.1(b)).
- ☐ the language of publication of the international application (under Rule 48.3(b)).
- ☐ the language of the translation furnished for the purposes of international preliminary examination (under Rules 55.2 and/or 55.3).

3. With regard to any nucleotide and/or amino acid sequence disclosed in the international application, the written opinion was drawn on the basis of the sequence listing:

- ☐ contained in the international application in printed form.
- ☐ filed together with the international application in computer readable form.
- ☐ furnished subsequently to this Authority in written form.
- ☐ furnished subsequently to this Authority in computer readable form.
- ☐ The statement that the subsequently furnished written sequence listing does not go beyond the disclosure in the international application as filed has been furnished.
- ☐ The statement that the information recorded in computer readable form is identical to the written sequence listing has been furnished.

4. ☒ The amendments have resulted in the cancellation of:

- ☒ the description, pages None _____
- ☒ the claims, Nos. None _____
- ☒ the drawings, sheets/fig None _____

5. ☐ This opinion has been drawn as if (none of) the amendments had not been made, since they have been considered to go beyond the disclosure as filed, as indicated in the Supplemental Box (Rule 70.2(c)).

* Replacement sheets which have been furnished to the receiving Office in response to an invitation under Article 14 are referred to in this opinion as "originally filed."

WRITTEN OPINION

International application No.
PCT/US02/30625**V. Reasoned statement under Rule 66.2(a)(ii) with regard to novelty, inventive step or industrial applicability; citations and explanations supporting such statement****1. STATEMENT**

Novelty (N)	Claims <u>1-9, 11</u>	YES
	Claims <u>10 and 12-22</u>	NO
Inventive Step (IS)	Claims <u>1-9</u>	YES
	Claims <u>10-22</u>	NO
Industrial Applicability (IA)	Claims <u>1-22</u>	YES
	Claims <u>NONE</u>	NO

2. CITATIONS AND EXPLANATIONS

Please See Continuation Sheet

WRITTEN OPINION

International application No.
PCT/US02/30625Supplemental Box
(To be used when the space in any of the preceding boxes is not sufficient)**TIME LIMIT:**

The time limit set for response to a Written Opinion may not be extended, 37 CFR 1.484(d). Any response received after the expiration of the time limit set in the Written Opinion will not be considered in preparing the International Preliminary Examination Report.

V. 2. Citations and Explanations:

Claims 10 and 12-22 lack novelty under PCT Article 33(2) as being anticipated by Bronson et al. (22 February 1994).

With respect to claim 10, 12-14, 16-19 and 21-22, Bronson et al. disclose (see figure 2, Col. 3, lines 2-43, Col. 7, lines 47-68, Col. 8, lines 1-68, and Col. 9, lines 1-47) a method for use during fabrication of a microelectronic device package, comprising: providing a package substrate (120) having a plurality of contact pads (140) on a surface thereof; attaching pins (170) to the pin contact pads (140) by pin solder reflow (190); and applying a no-flow encapsulation material (e.g., epoxy resin 200) about solder joints associated with the pins (170), to protect the circuitry from the environment. Bronson et al. further disclose a semiconductor die (150) connected to the package substrate (120). Although Bronson et al. do not explicitly teach the semiconductor die (150) having a plurality of bonding pads coupled to the pins through the substrate (120), such bonding pads taken to be inherent in chip 20 since the means of electrically connecting the semiconductor die to the substrate via solder balls (160) is disclosed and it is apparent that some type of bonding pads must be present on the chip surface for solder balls (160) electrically bonding to, and the solder balls (160) are electrically connected to the pins (17) through the substrate (120).

Regarding claims 15 and 20, Bronson et al. do disclose that the epoxy resin (200) is preferred as a resin available under trademark Hysol FP0045 from the Dexter Corporation (Col. 9, lines 11-22), and this epoxy resin is included a polymer material as evidenced by Hermansen et al. (US 5,759,730, Col. 1, lines 44+, Col. 2, lines 14-18, and Col. 2, lines 46+).

Claims 10, 12-14, 16-18 and 21-22 lack novelty under PCT Article 33(2) as being anticipated by Ozono et al. (03 April 2001).

With respect to claim 10, 12-14, 16-19 and 21-22, Ozono et al. disclose (see figures 6A-6B-6C) a method for use during fabrication of a microelectronic device package, comprising: providing a package substrate (21) having a plurality of pin contact pads (22) on a surface thereof; attaching pins (27) to the pin contact pads (22) by pin solder reflow (23); and applying a no-flow encapsulation material (e.g., adhesive resin 4) about solder joints associated with the pins (27), to prevent the movement of the pins when the substrate is subjected to high temperatures. Ozono et al. further disclose a semiconductor die (25) connected to the package substrate (21), wherein the die (25) having bond pads (see figure 6C) that are conductively coupled to the pins (27).

Claims 10 and 12-17 lack novelty under PCT Article 33(2) as being anticipated by Bross et al. (19 April 1994).

With respect to claim 10 and 12-17, Bross et al. disclose (see figure 1B) a method for use during fabrication of a microelectronic device package, comprising: providing a package substrate (5) having a plurality of pin contact pads (6) on a surface thereof; attaching pins (2) to the pin contact pads (6) by pin solder reflow (4); and applying a no-flow encapsulation material (e.g., a polyimide-based material 3) about solder joints associated with the pins (2), to prevent the movement of the pins when the substrate is subjected to high temperatures.

Claim 11 lacks an inventive step under PCT Article 33(3) as being obvious over Bronson et al. (22 February 1994).

Form PCT/PEA/408 (Supplemental Box) (July 1998)

WRITTEN OPINION

International application No.
PCT/US02/30625

Supplemental Box

(To be used when the space in any of the preceding boxes is not sufficient)

Bronson et al. discloses the claimed invention as detailed above except for using a jig to attach the pins to the substrate.

However, pinning jig is a known tool in the art used to attach conductive pins to a substrate or a chip for soldering or bonding. It would have been obvious to one of ordinary skill in the art at the time the invention was made to use the pinning jig to attach the pins to the pin contact pads on the substrate for soldering the pins to the pads, since such tool is conventional in the art to bond the pins to the pads on the substrate.

Claims 1-9 meet the criteria set out in PCT Article 33(2)-(3), because the prior art does not teach or fairly suggest the method steps of applying a polymer material to a surface of the package substrate, attaching pins to the package substrate, through the polymer material, by solder reflow, and these method steps could not easily be conceived of even by a person skilled in the art in the light of the features disclosed in the cited prior arts, such as Bronson et al., wherein Bronson et al. teach the encapsulating material to be applied to the substrate after the step of attaching the pins to the substrate.

Claims 1-22 meet the criteria set out in PCT Article 33(4), and thus claims 1-22 are industrial applicability because the subject matter claimed can be made or used in industry.

NEW CITATIONS

US 6,209,196 B1 (Ozono et al.) 03 April 2001, see figures 6A-6B-6C, column 5, lines 17-65.

US 5,759,730 (Hermansen et al.) 02 June 1998, column 1, lines 44-45, column 2, lines 14+ and lines 46-50.

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